

In the Claims:

Please amend the claims as follows:

1. (Currently Amended) A [[C]]configuration [[100]] comprising: an active optical component [[20]] that is electrically connected to a flexible electronic board [[10]], the active optical component being designed to be aligned with an optical system, [[characterized in that]] characterized in that the electronic board is a flexible circuit with a high density of interconnections, called a HDI flexible circuit, with an upper longitudinal surface [[10a]] that comprises a metallic brazing sector [[6]] in contact with a microwave transmission path [[3]] of the HDI flexible circuit, [[and [also characterized] in that]] and also characterized in that the active optical component on one of its surfaces [[20a]], i.e. the contact surface, comprises a metallic contact sector [[21]] that coincides directly with the metallic brazing sector by turning said active optical component over onto the HDI flexible circuit.
2. (Currently Amended) The [[C]]configuration [[100]] ~~as claimed in~~ of claim 1, [[characterized in that]] characterized in that the metallic brazing sector [[6]] comprises a network of metallic brazing contact studs [[61, 62]] with a diameter of roughly 30 μm .
3. (Currently Amended) The [[C]]configuration [[100]] ~~as claimed in~~ of claim 2, [[characterized in that]] characterized in that the upper longitudinal surface [[10a]] of the HDI flexible circuit [[10]] comprises a zone of electrical insulation [[51]] in an essentially annular configuration around one of the ends of the microwave transmission path [[3]] and extending through a flared electrical insulation zone [[52]], [[and [also characterized] in that]] and also characterized in that one of said metallic brazing contact studs, i.e. the central contact [[61]], is located on said end and the other metallic brazing contact studs [[62]] are distributed essentially in a semi-circle or circles on a ground conductive zone [[4]] in the vicinity of the side of said annular electrical insulation zone.
4. (Currently Amended) The [[C]]configuration [[100]] ~~as claimed in~~ of claim 3,

~~[[characterized in that]]~~ characterized in that the flared electrical insulation zone ~~[[((52))]]~~ ends in a narrowed electrical insulation zone ~~[[((53))]]~~.

5. (Currently Amended) The ~~[[C]]~~ configuration ~~[[((100))]]~~ ~~as claimed in one of claims of~~ claim 1 ~~[[to 4]]~~, ~~[[characterized in that]]~~ characterized in that the active optical component can be chosen from among a photodiode ~~[[((20))]]~~ that is able to receive modulated optical signal by the longitudinal surface ~~[[((20b))]]~~, i.e. the receiving surface, parallel to the contact surface ~~[[((20a))]]~~, and a laser that is able to supply modulated optical signals by the longitudinal surface, i.e. the transmission surface, parallel to the contact surface.

6. (Currently Amended) The ~~[[C]]~~ configuration ~~[[((100))]]~~ ~~as claimed in one of~~ ~~[[claims]]~~ claim 1 ~~[[to 5]]~~, ~~[[characterized in that]]~~ characterized in that the upper longitudinal surface ~~[[((10a))]]~~ of the HDI flexible circuit ~~[[((10))]]~~ comprises another metallic brazing sector ~~[[((7))]]~~, said other sector being in contact with one end of the microwave transmission path ~~[[((3))]]~~ and with another microwave transmission path ~~[[((3'))]]~~ of the HDI flexible circuit ~~[[((10))]]~~, ~~[[and [also~~ characterized] in that]] and also characterized in that it comprises an active electronic component ~~[[((50))]]~~ that has, on one of its surfaces, i.e. the contact surface ~~[[((50a))]]~~, a metallic contact sector that coincides directly with said other metallic brazing sector by turning the active electronic component over onto the HDI flexible circuit.

7. (Currently Amended) An ~~[[O]]~~ optoelectronic device ~~[[((300))]]~~ that is equipped with a box ~~[[((60))]]~~ ~~[[characterized in that]]~~ characterized in that it comprises the configuration ~~[[((100))]]~~ as claimed in ~~one of claims~~ claim 1 ~~[[to 6]]~~ and an optical system ~~[[((30))]]~~ aligned with the active optical component ~~[[((20))]]~~, the configuration and the optical system being kept in the box.

8. (Currently Amended) The ~~[[O]]~~ optoelectronic device ~~[[((300))]]~~ ~~as claimed in~~ of claim 7, ~~[[characterized in that]]~~ characterized in that when the active optical component ~~[[((20))]]~~ is chosen from among said photodiode and said laser, the HDI flexible circuit ~~[[((10))]]~~ is bent and the upper longitudinal surface ~~[[((10a))]]~~ comprises a first part, with respect to the bottom of the box ~~[[((61))]]~~ extended by a second part containing said brazing sector ~~[[((6))]]~~ with respect to one

of the lateral transverse surfaces [(62)] of the box.

9. (Currently Amended) The [(O)]optoelectronic device [(300)] ~~as claimed in~~ of claim 8, ~~[(characterized in that)]~~ characterized in that the receiving surface [(20b)] of the active optical component [(20)] is attached by an optically transparent adhesive [(40)] to one end of an optical fiber [(30)] integral with said lateral transverse surface [(62)] of the box.

10. (Currently Amended) A [(P)]process of manufacture of a configuration [(100)] as claimed in ~~one of claims~~ claim 1 [(to 6)], ~~[(characterized in that)]~~ characterized in that it comprises the following stages:

- the stage of formation of the metallic brazing sector [(6)] of the HDI flexible circuit [(10)] by physical vapor phase deposition,
- the stage of formation of the metallic contact sector [(21)] of the active optical component [(20)],
- the stage of installation of the active optical component [(20)] on the HDI flexible circuit by turning it over and brazing.

11. (Currently Amended) The [(P)]process of manufacture of a configuration [(100)] ~~as claimed in~~ of claim 10, ~~[(characterized in that)]~~ characterized in that it comprises the following stages

- the stage of formation of another metallic brazing sector (7) of the HDI flexible circuit [(10)] by physical vapor phase deposition,
the stage of formation of the metallic contact sector of the active electronic component [(50)],
the stage of installation of the active electronic component on the HDI flexible circuit by turning it over and brazing.

12. (Currently Amended) A [(P)]process of manufacture of an optoelectronic device [(300)] ~~as claimed in one of~~ [(claims)] claim 8 [(or 9)], ~~[(characterized in that)]~~ characterized in that it comprises the stages of manufacture of a configuration [(100)] ~~as claimed in one of~~

[[claims]] claim 10 or 11 ~~[[and [also characterized] in that]]~~ and also characterized in that it comprises a stage of supporting the configuration and the optical system in said box including the bending of the HDI flexible circuit ~~[[10]]~~.

13. (Currently Amended) The ~~[[P]]~~process of manufacture of an optoelectronic device ~~[[300]] as claimed in~~ of claim 12, [[characterized in that]] characterized in that the optical system comprises an optical fiber ~~[[30]]~~, wherein the stage of supporting the configuration and the optical fiber in the box includes the following:

- bonding the optical fiber in one of the lateral transverse surfaces ~~[[62]]~~ and bonding the active electronic component ~~[[50]]~~ in the bottom of the box ~~[[61]]~~,
- soldering the end of the HDI flexible circuit ~~[[10]]~~ to one interconnection located at the level of the other of the lateral transverse surfaces of the box ~~[[63]]~~.